



# CALL FOR PAPERS

**ICEST 2021**  
**Jan 21-22, 2021**  
**London, United Kingdom**

The International Research Conference is a federated organization dedicated to bringing together a significant number of diverse scholarly events for presentation within the conference program. Events will run over a span of time during the conference depending on the number and length of the presentations.

ICEST 2021 : International Conference on Electronic Soldering Technology is the premier interdisciplinary forum for the presentation of new advances and research results in the fields of Electronic Soldering Technology. The conference will bring together leading academic scientists, researchers and scholars in the domain of interest from around the world. Topics of interest for submission include, but are not limited to:

Soldering science and technology  
Soldering and surface mount technology  
Novel soldering processes and new solder alloys  
Surface mount technology (SMT)  
Surface mount assembly  
Advanced packaging technologies and 3D interconnects  
Flip chip/BGA/SiP/TSV  
Novel substrates and embedded components

Solderable finishes and coatings  
Screen printing  
Conductive adhesives and conformal coatings  
Reliability  
Quality control  
Inspection and testing  
Rework and repair  
Environmental aspects